

# Aircraft Structures NDT with ET Arrays

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01752

Jenteksensors.com

# Types of Eddy Current Arrays

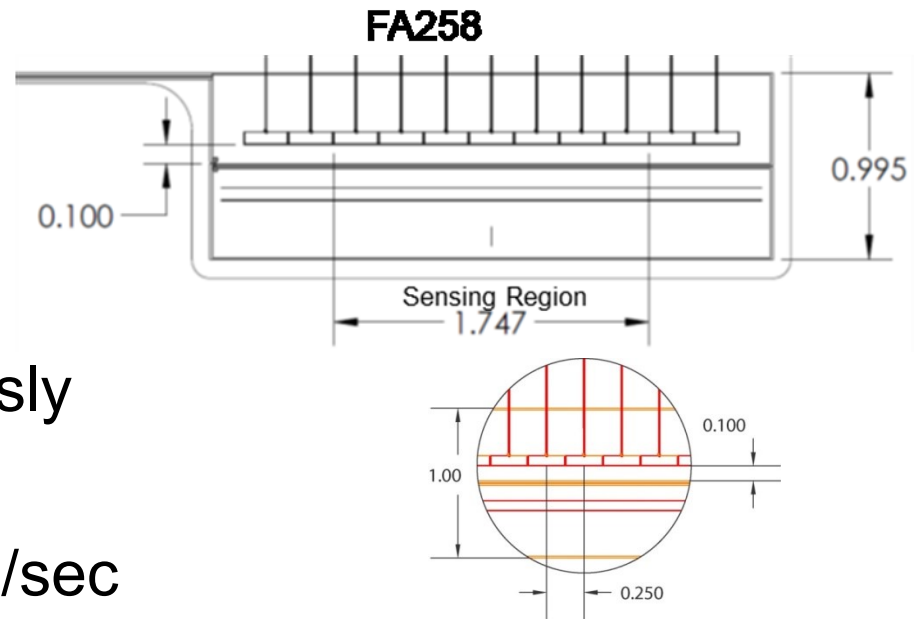
- 1. Compilations of single eddy current testing (ET) coils**
  - Used independently (either in parallel or multiplexed)
  - Mounted on a shuttle that is rigid and shaped similar to the part
  - **Challenges include: rigidity, cross talk for parallel operation, variability channel to channel, response variation across array, etc.**
- 2. Arrays of flat spiral coils** or multiple layered coils that can act as both drive and sense elements
  - Multiplexed in groups of channels (typically 4 or 8 at a time)
  - Must avoid exciting neighboring coils due to cross talk
  - **Challenges include: variable channel performance, crack response variations across array, variable directional sensitivity across array, curvature effects and rigidity due to complex cabling issues.**
- 3. Single rectangular drive with linear array of square sense elements MWM-Arrays**
  - Fully parallel data acquisition from all channels
  - No significant cross talk
  - Designed for physics model-based analysis methods
  - **Challenges include: larger cables for many channels, culture change is a hurdle for some customers**

# jET with MWM-Array Technology (larger channel count systems called GS8200 use same technology)

**jET<sup>®</sup>**



**MWM<sup>®</sup>-Array**



- 3 frequencies simultaneously
- 7 channels simultaneously
- Up to 1000 measurements/sec per channel

**MWM-Array**

- Designed for model based methods
- Drive sense gap determines depth of penetration



# Fully Parallel Digital electronics, with MWM-Array Advantages

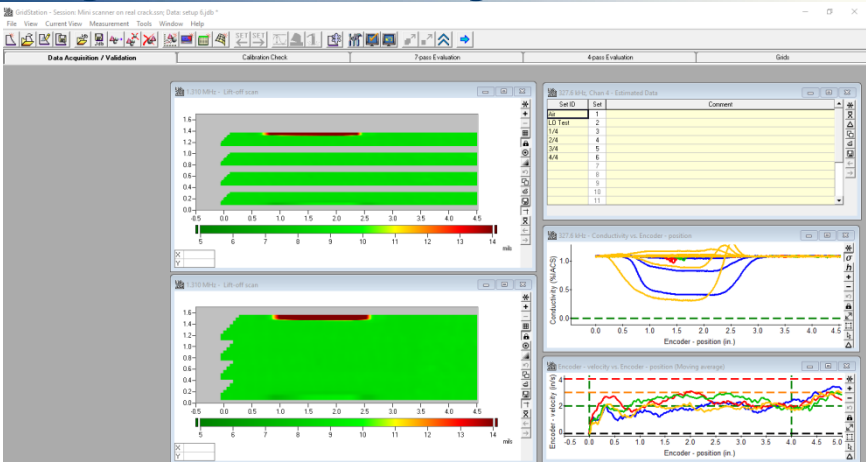
- 1. Sensor: Designed for model-based multivariate inverse methods (MIMs)**
  - Designed with simple linear drives and square sensing elements
  - No significant cross talk between elements.
  - Enables more robust results, such as **rescaling of the crack response** for variable liftoff when scanning a curved surface.
- 2. Electronics: Simultaneous data acquisition at up to 3 frequencies**
  - Needed to measure multiple properties, such as independent 1<sup>st</sup> and 2<sup>nd</sup> layer corrosion imaging independent of gap between layers.
  - Both complex impedance components simultaneously to retain data integrity and support model based methods
- 3. Electronics & Sensor: Enable fully parallel (simultaneous) acquisition from 7 sensing elements**
  - Needed to reliably detect and size cracks
  - Needed to reliably detect cracks at edges
  - Needed to ensure consistent coverage of the inspection surface
  - Needed to rescale crack response for position within the array

# Probability of Inspection (POI)

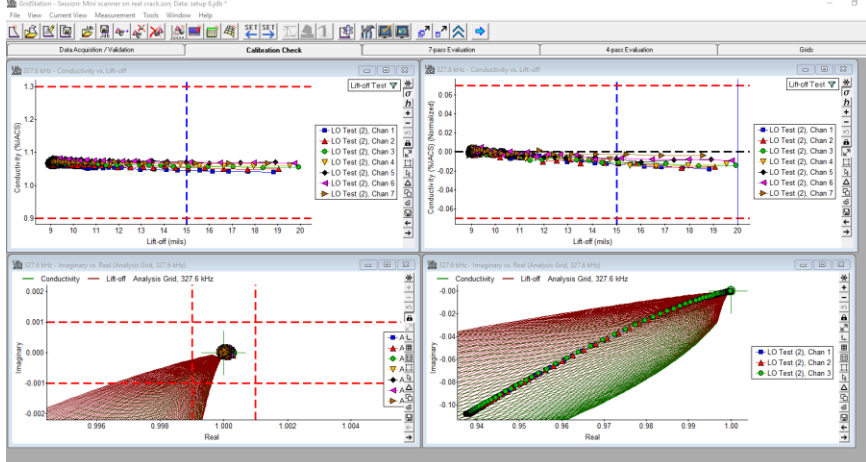
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1. **Actual POD = POD Study POD x POI**
2. **Need: Easy way for Inspector to determine that**  
  
**“POI is essentially 100%”**
3. **Solution: Model-Based Data Analysis and Visualization**
  - Model-Based Inverse Methods (MIMs)
  - Calibration verification
  - C-Scan and B-Scan visualization
  - Rescaling of defect responses for other variables such as
    - Lift-off
    - Position within Array
    - Position relative to edges

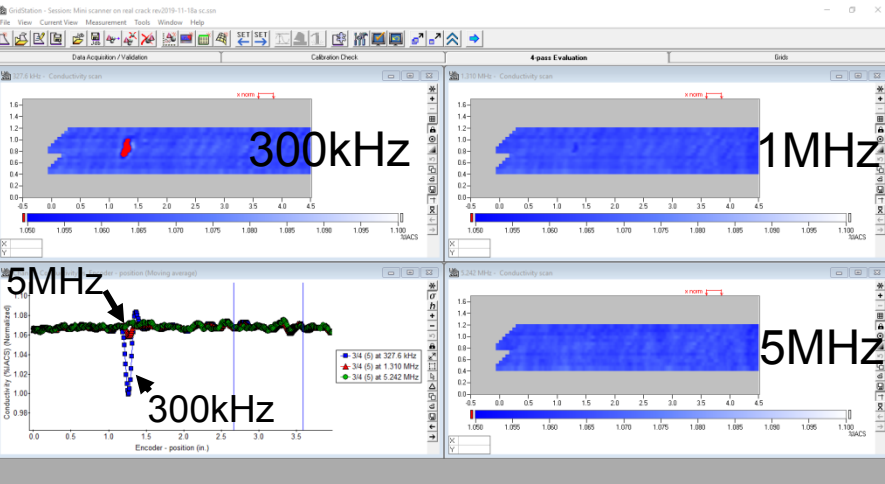
# Software "Tabs" for window groups, for easy data analysis and POI Determination



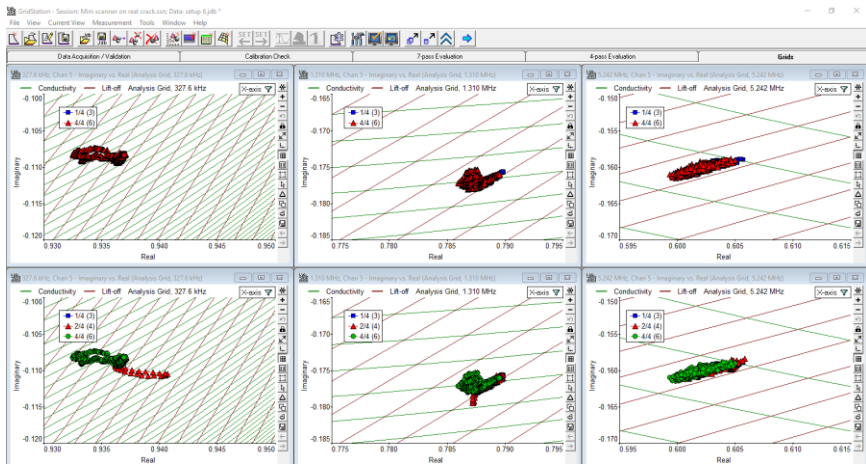
**Lift-off and coverage verification**



**Air Calibration & Cal Check (Air and liftoff)**



**Crack detection**



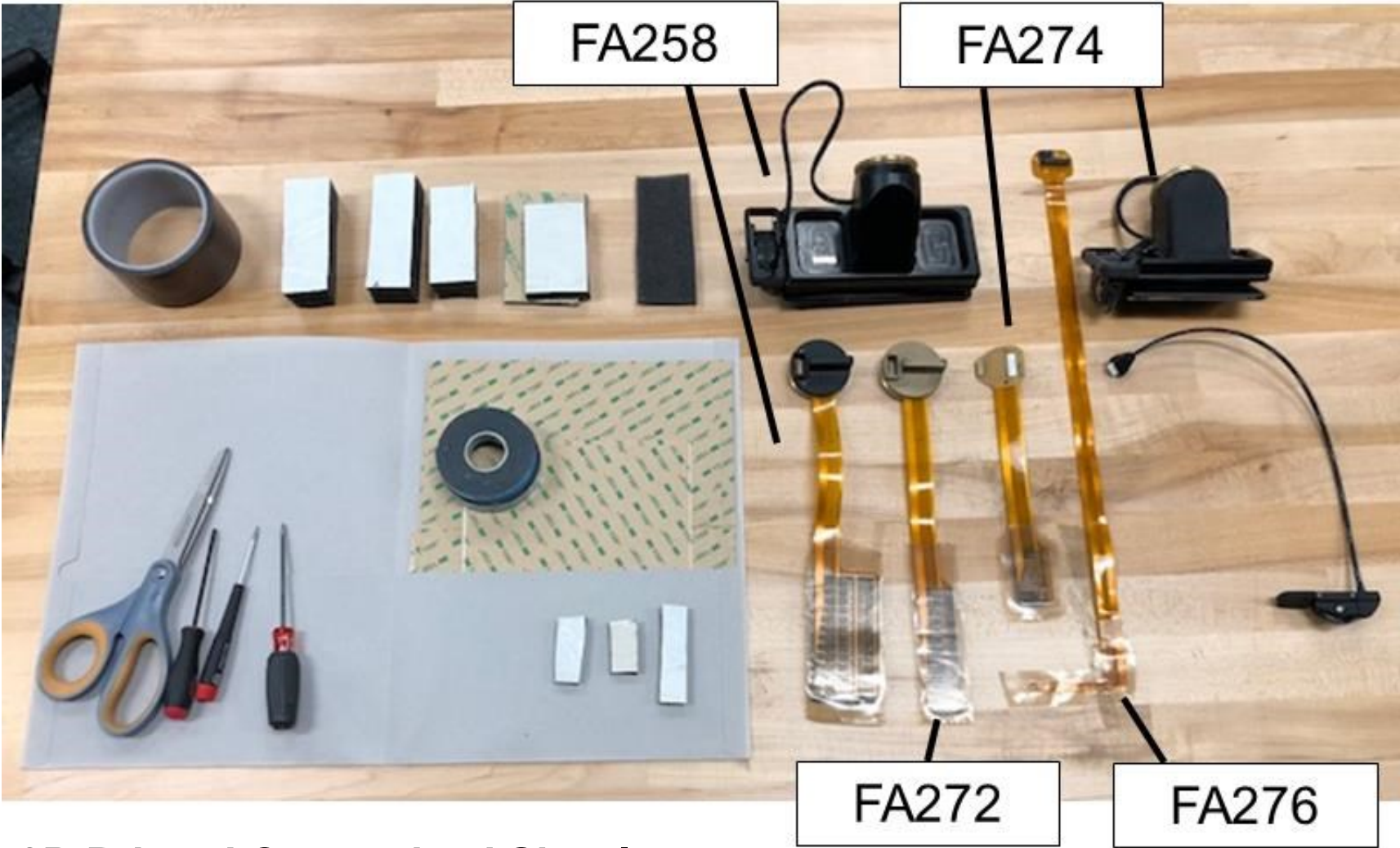
**Model-Based visualization**

# Example Aircraft Structures NDT Applications for MWM-Arrays

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1. **Corrosion imaging**
2. **Buried crack detection**
3. **Bolt hole inspection**
4. **Surface crack detection**
5. **Coating characterization**
6. Detection of cracks in steel through coatings
7. Friction Stir Weld (FSW) and other weld inspection
8. Detection of 1<sup>st</sup> and 2<sup>nd</sup> layer cracks at fasteners
9. Layer-by-Layer in process additive manufactured (AM) metal part inspection and post process NDT
10. Residual stress/stress monitoring, and cold work assessment for various but not all alloys

# Sensor Kits for adaptation to new applications



**3D Printed Customized Shuttles**



# Picking the Right MWM-Array Sensor

*(Depth of Penetration is NOT Depth of Sensitivity)*

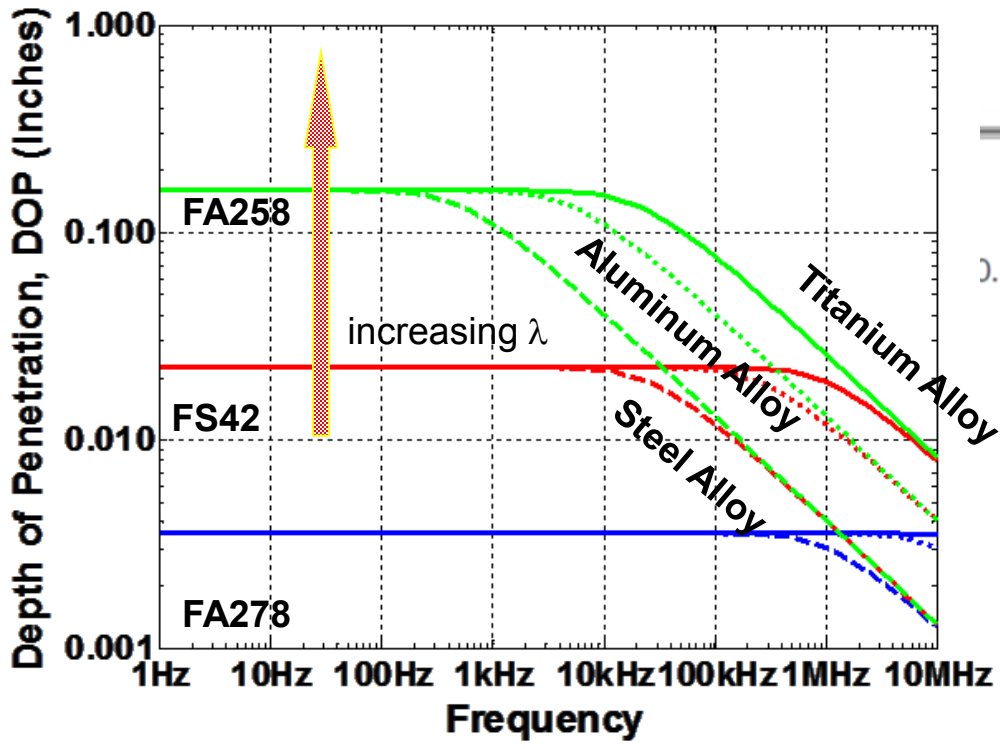
Field Variation with Depth  $\approx e^{-\Gamma_n z}$

$$\Gamma_n = \sqrt{(2\pi n / \lambda)^2 + j2 / \delta^2}$$

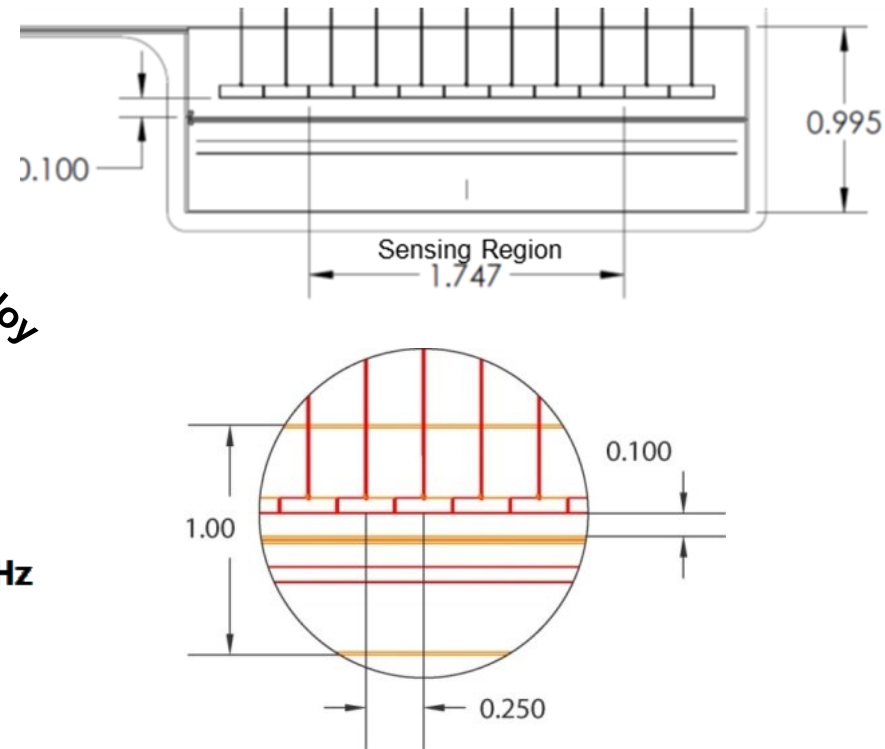
Spatial Fourier Mode Depth of Penetration =  $1/\text{Re}(\Gamma_n)$

Low frequency asymptote =  $\lambda/2\pi$

Skin depth:  $\delta = \sqrt{\frac{1}{\pi f \mu \sigma}}$



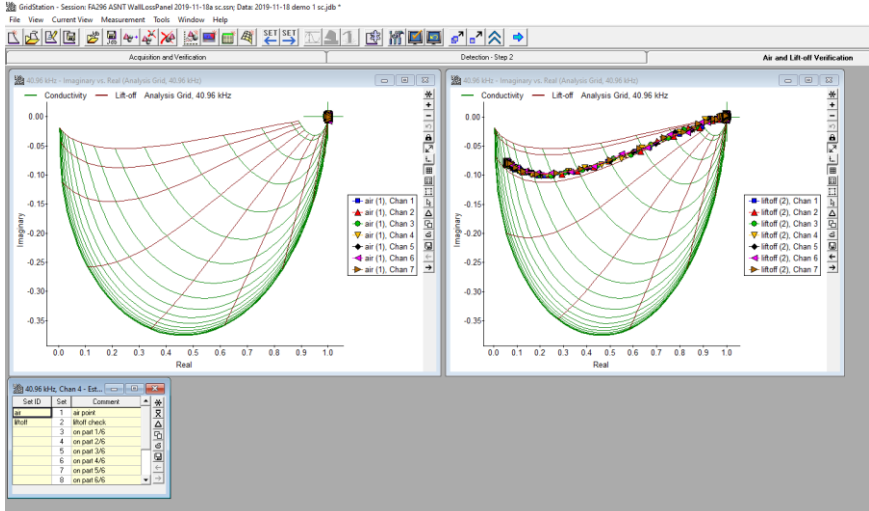
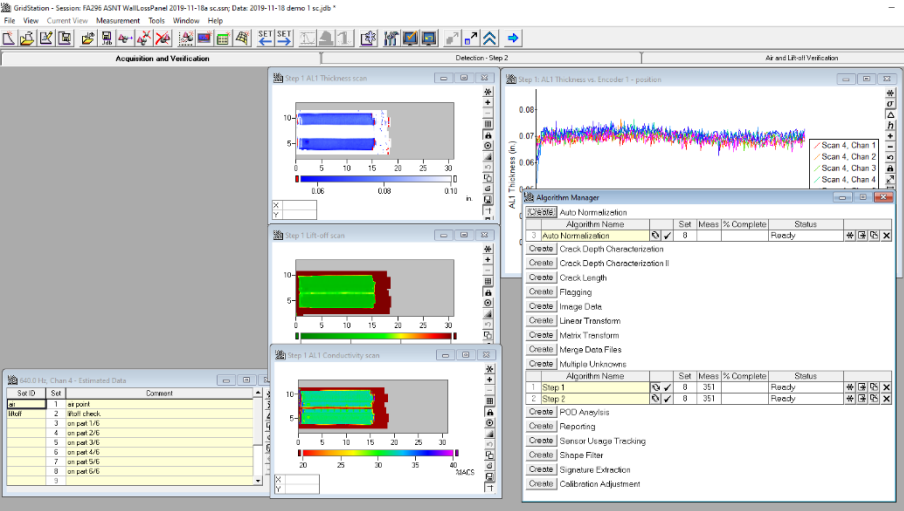
## MWM® Array FA258



# Corrosion Imaging Performance Study Ongoing

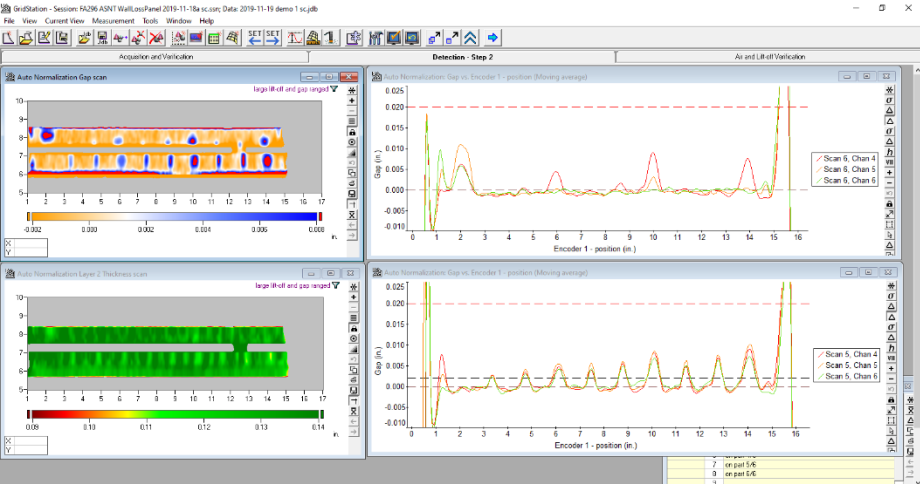


# Corrosion Loss Imaging and POI Verification



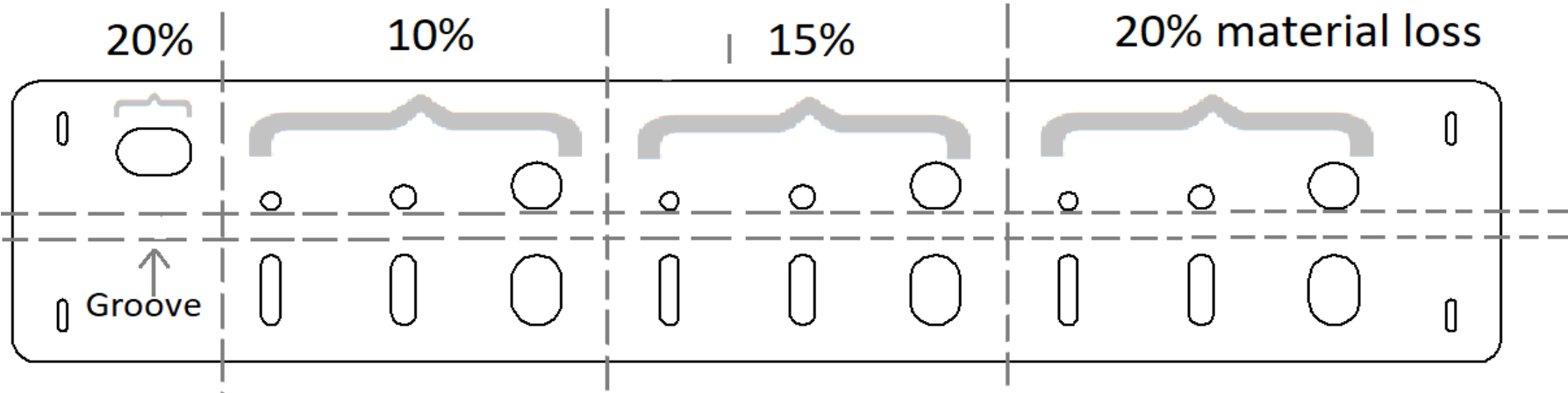
**Liftoff & coverage verification**

**Air Calibration & Cal Check (Air and liftoff)**

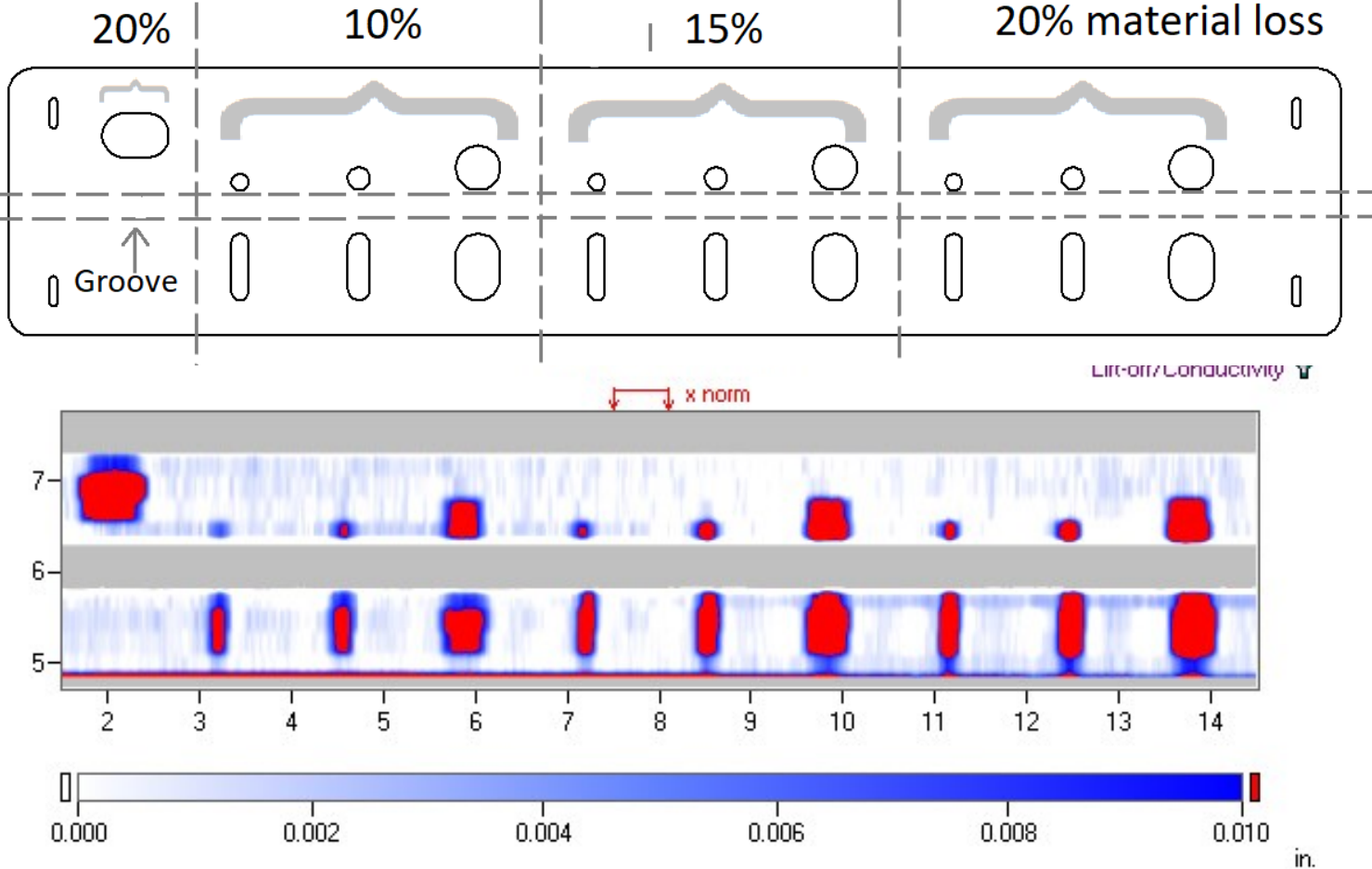


**C-Scan and B-Scan data visualizations**

# 15 inch Corrosion Loss Sample

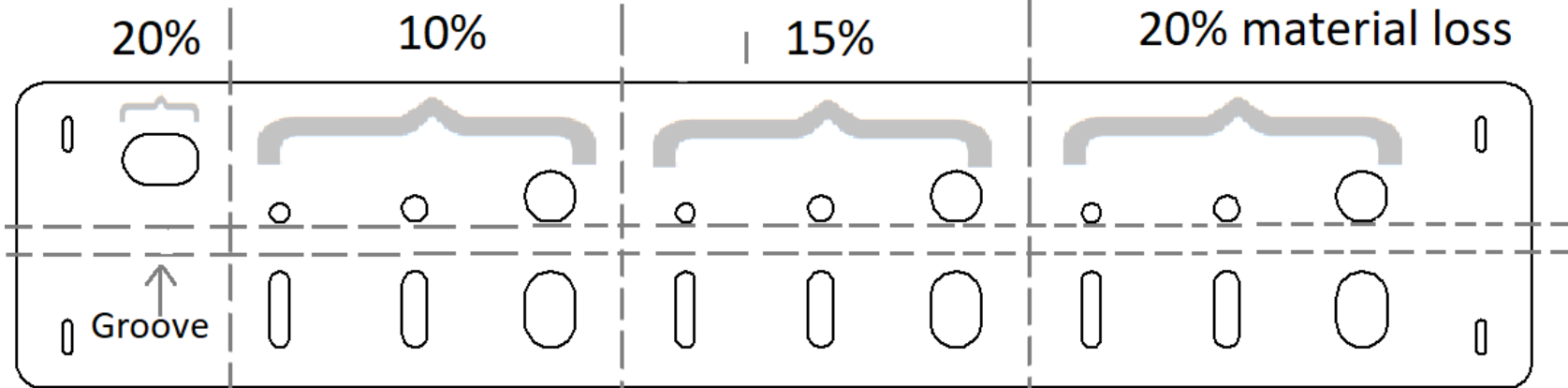


# FA296: 15 inch Corrosion Loss Sample (1)

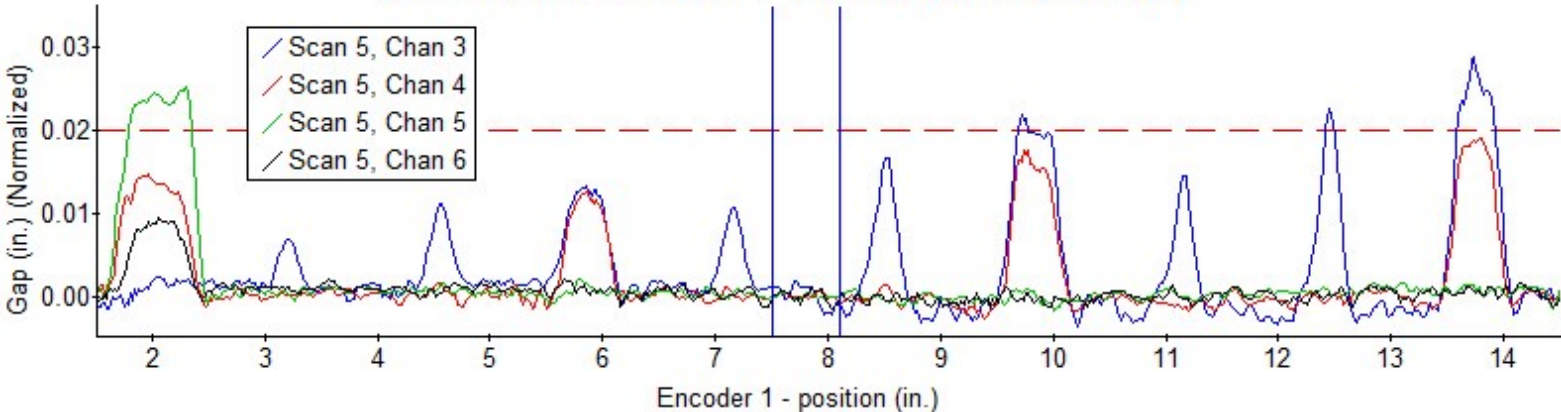


Filtered and normalized C-scan of Gap data across the corrosion defect locations.

# FA296: 15 inch Corrosion Loss Sample Holes (2)

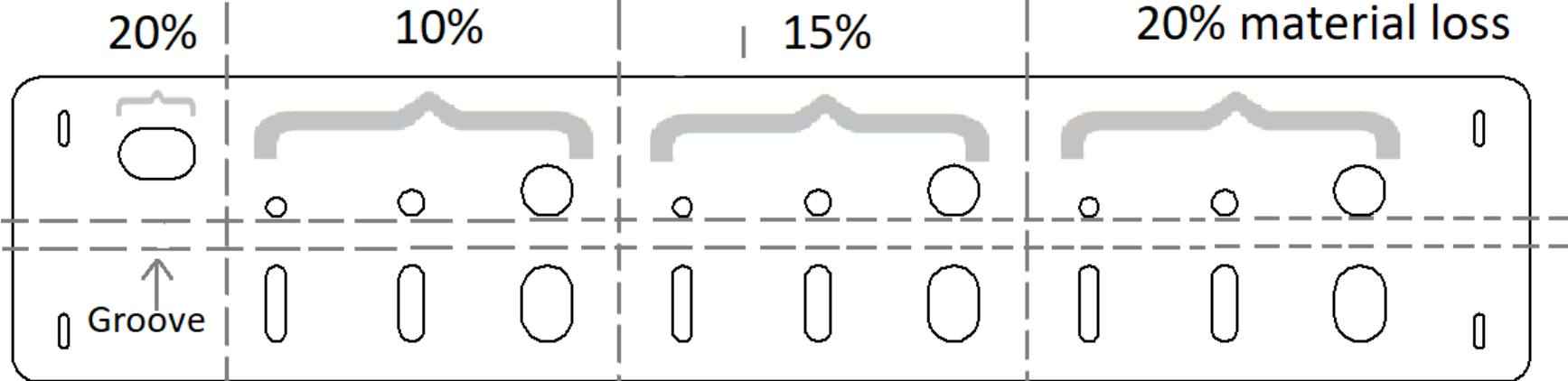


Step 2: Gap vs. Encoder 1 - position (Moving average)

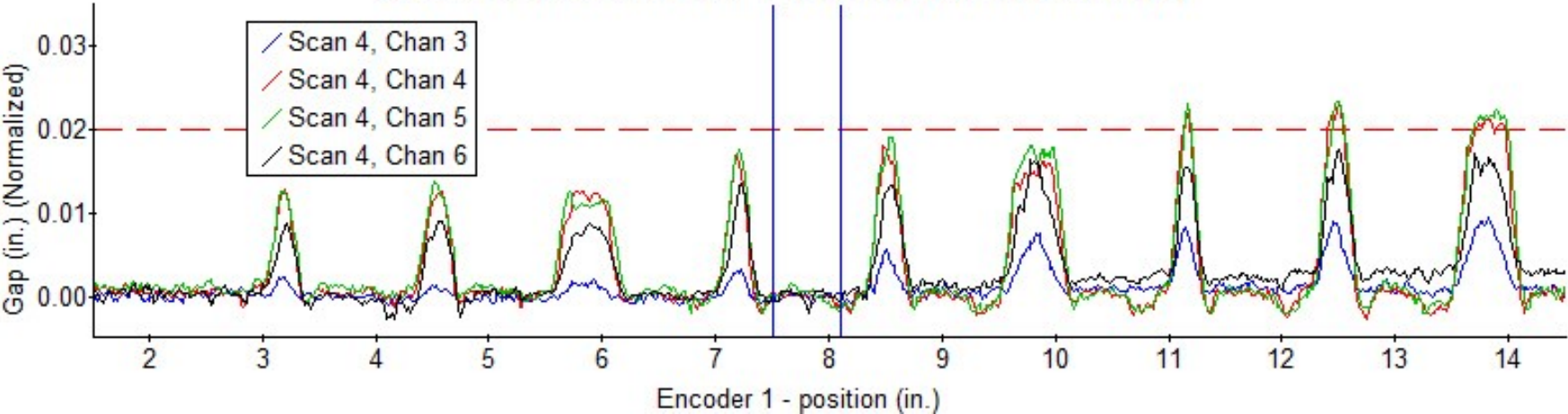


Normalized B-scan of Gap data across the flat bottom hole defect locations.

# FA296: 15 inch Corrosion Loss Sample Slots (3)



Step 2: Gap vs. Encoder 1 - position (Moving average)

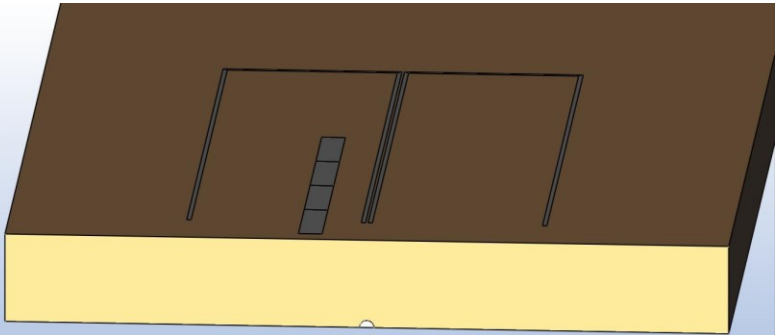


Normalized B-scan of Gap data across the flat bottom slot defect locations.

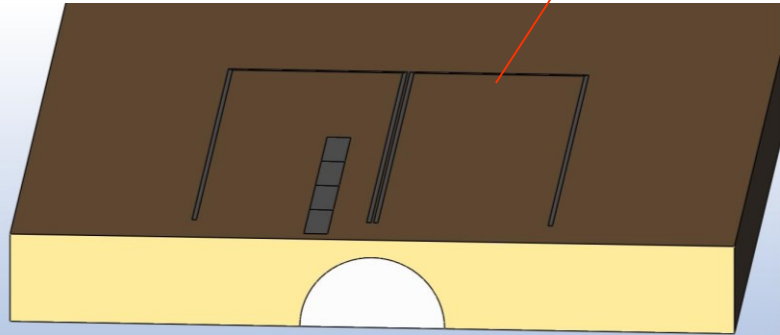
# Subsurface crack modeling option

- Standard 2D models for sensor response
  - Use JENTEK Grid Methods to obtain conductivity values for several frequencies
  - Higher frequencies will provide a measure of near surface region conductivity
  - Lower frequencies provide higher sensitivity to subsurface cracks
- 3D models to better correlate scan information to crack dimensions
  - Example: FA258 over a 0.25 in. plate with small and large cracks (for 1%IACS)

Smaller Flaw

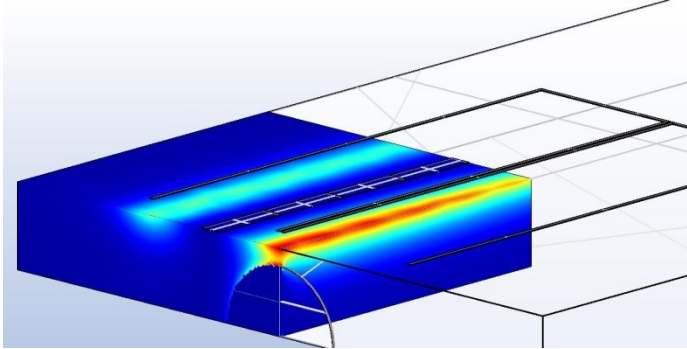
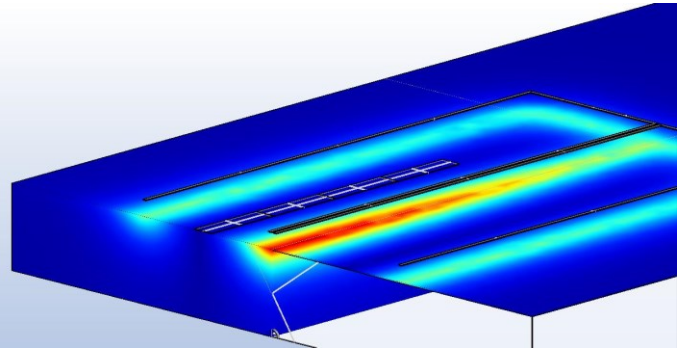


Larger Flaw



1/2 of FA258 MWM-Array

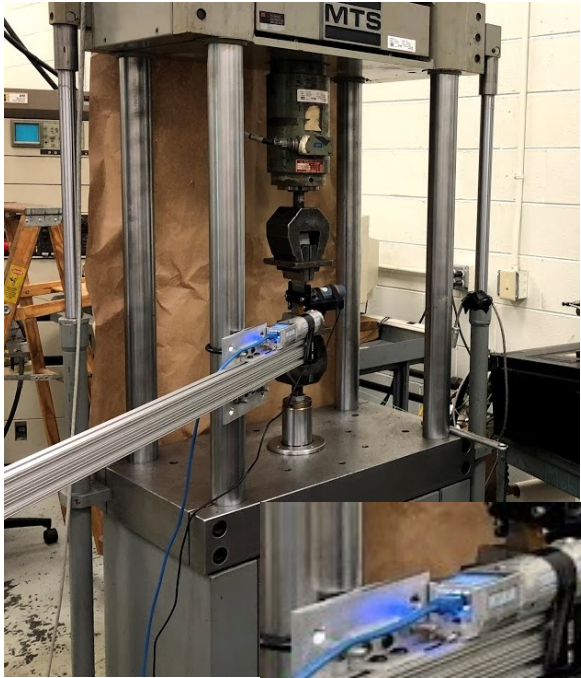
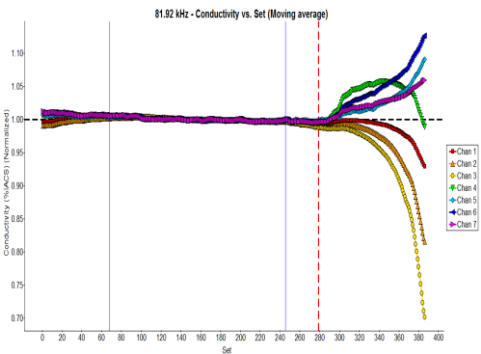
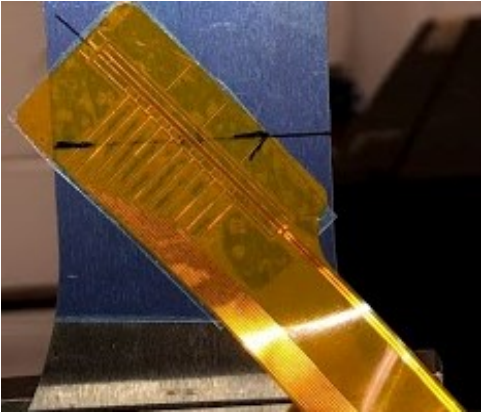
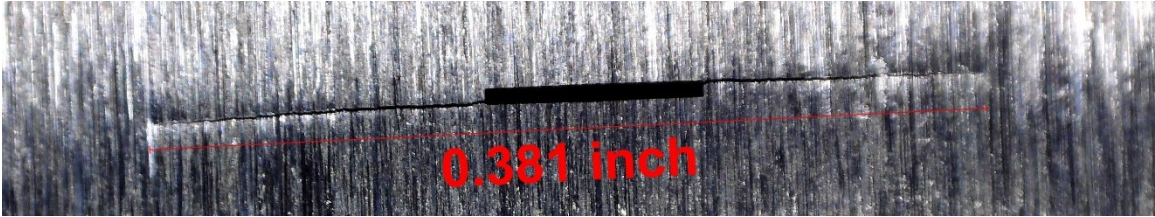
1/2 of physical geometry (using symmetry)



Induced current density contour plots [100 kHz; 0.05 in. lift-off; 0.4 in. long larger notch]



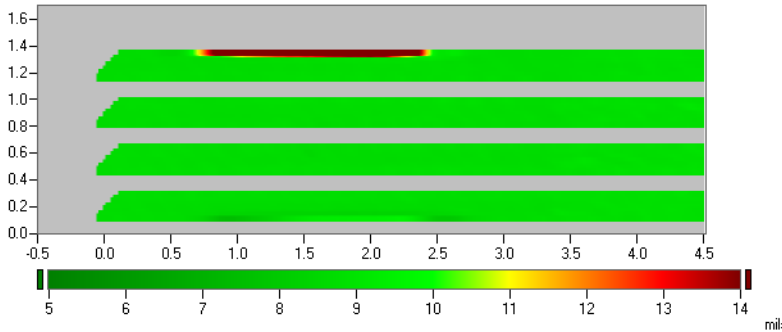
# Real Crack Fabrication, Using MWM-Array Monitoring



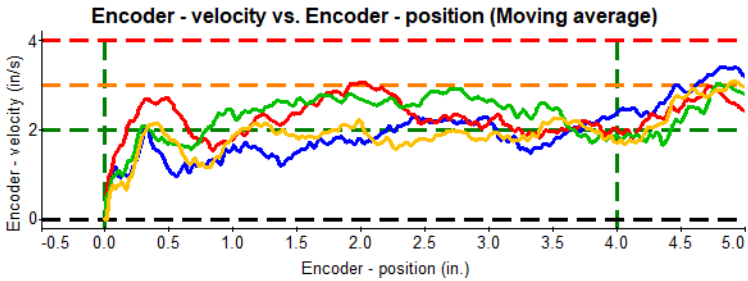
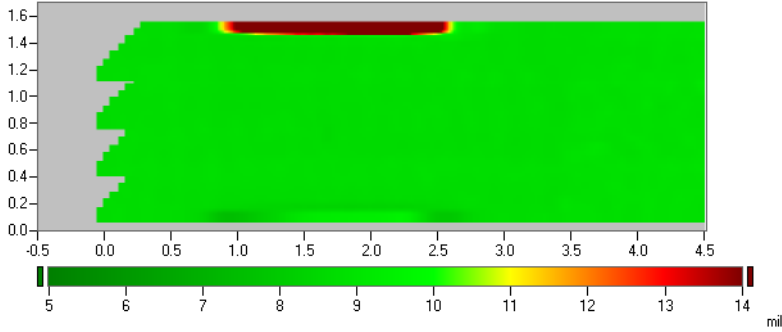
# Data Validation and Inspector Feedback



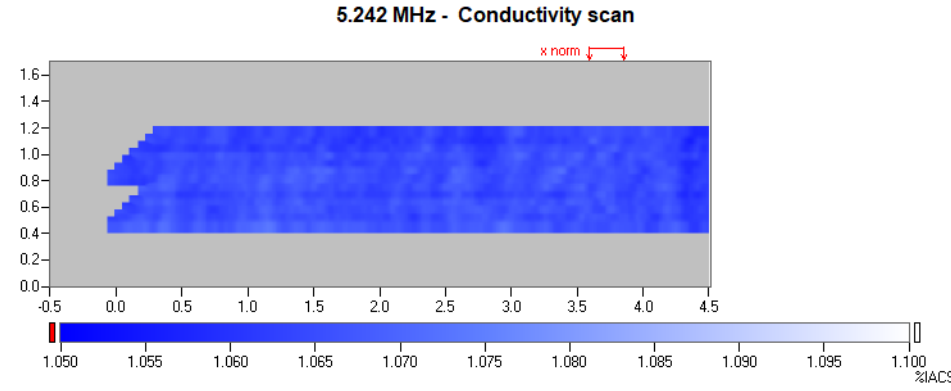
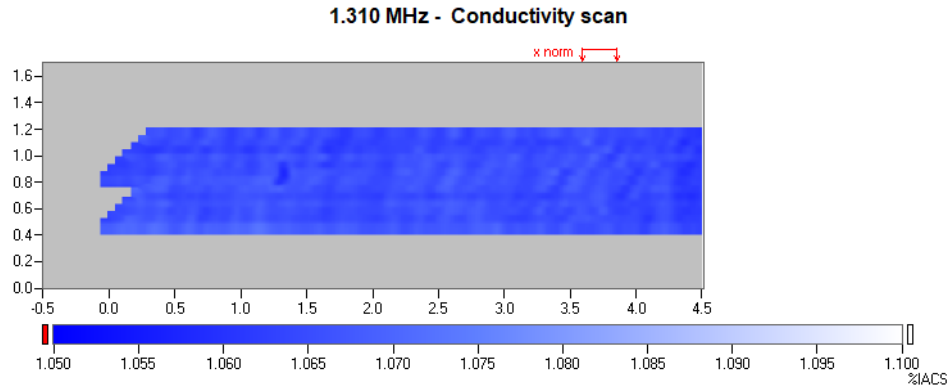
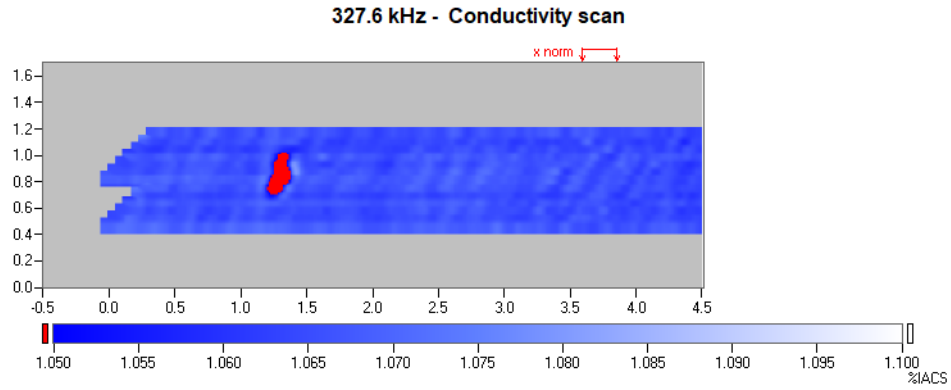
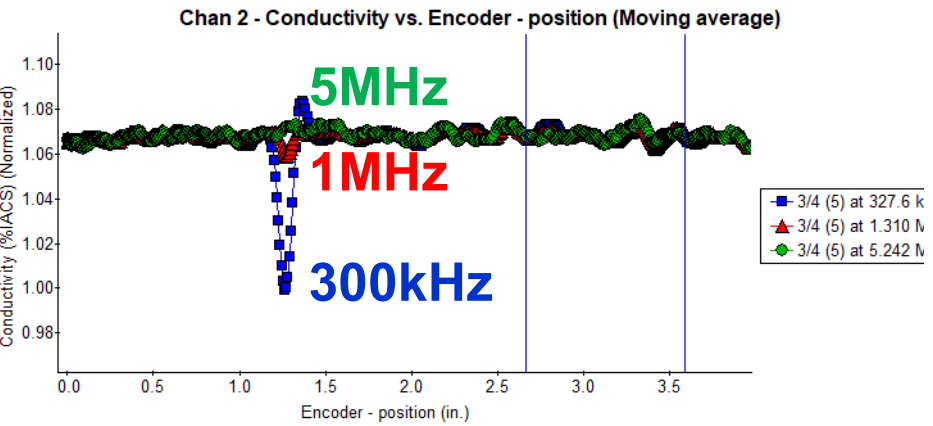
1.310 MHz - Lift-off scan



1.310 MHz - Lift-off scan

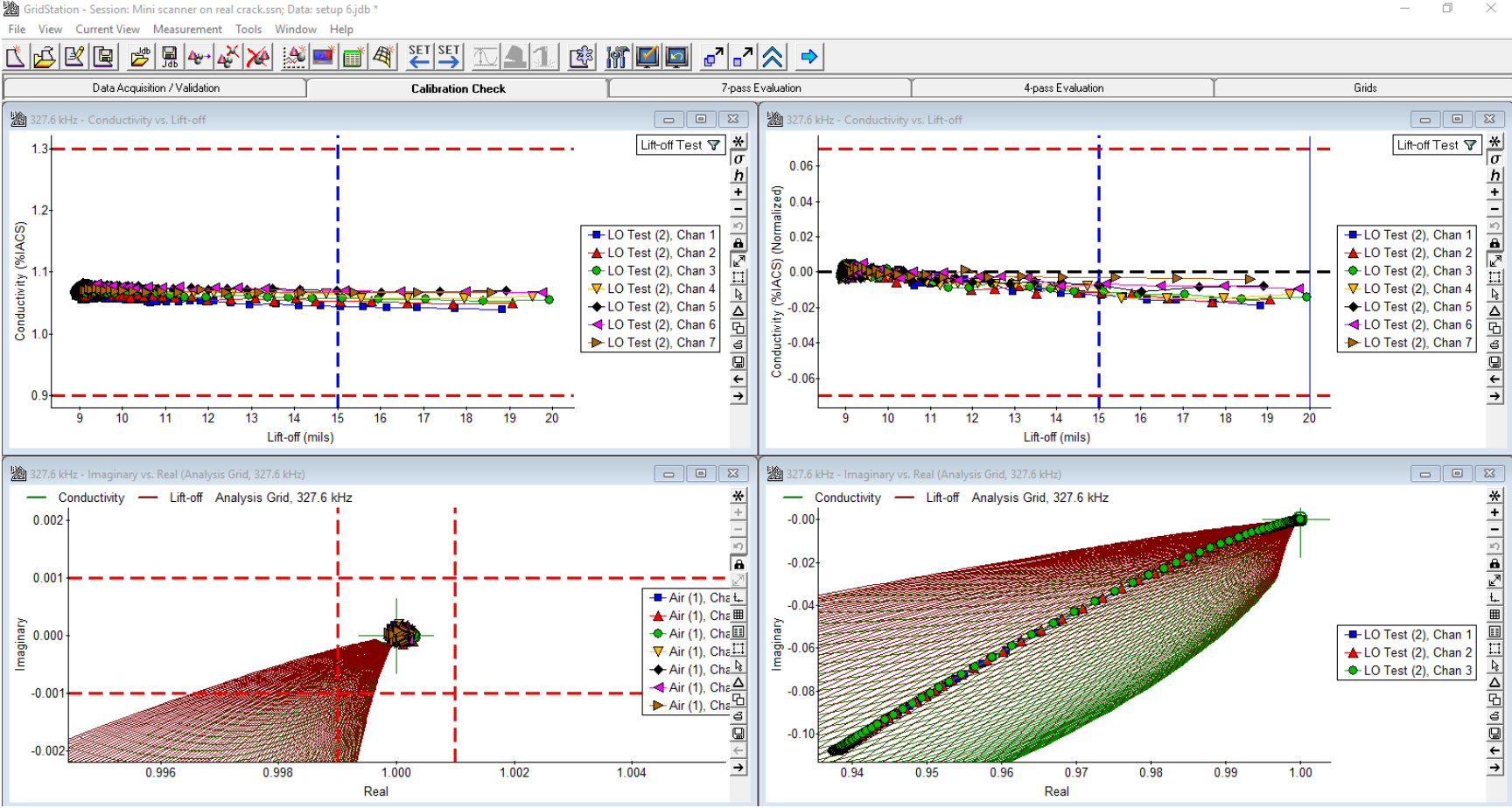


# Subsurface Crack Detection – 3 Frequency

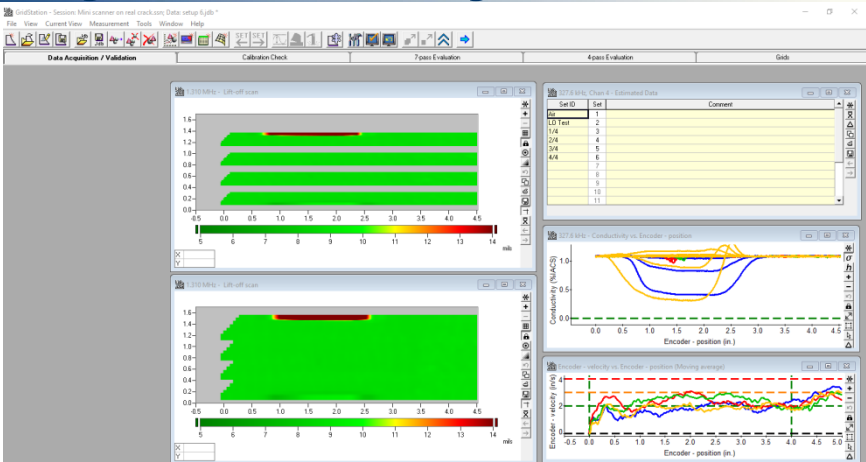


# Calibration Verification (POD = Assumed POD x POI)

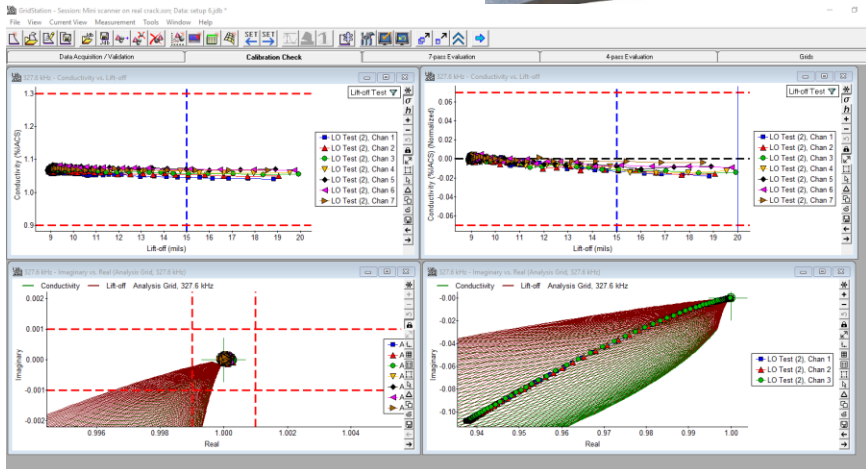
## Inspectors must always verify that the POI (Probability of Inspection) is essentially 100%



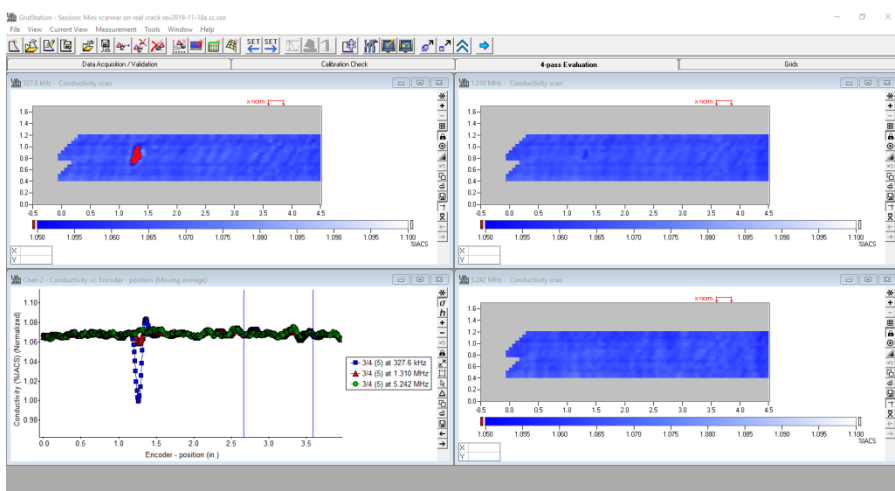
# Software "Tabs" for window groups, for easy data analysis and POI Determination



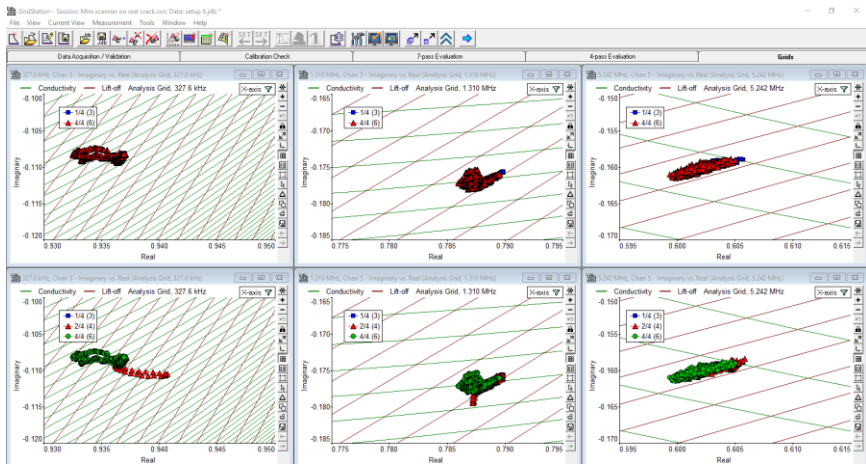
Lift-off and coverage verification



Calibration Check (Air and liftoff)



Crack detection

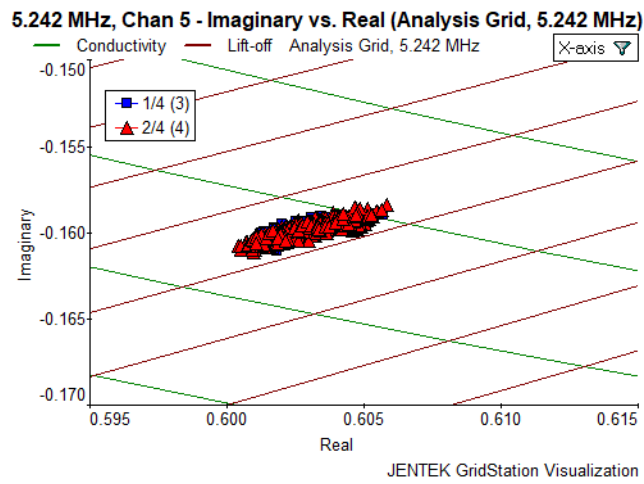
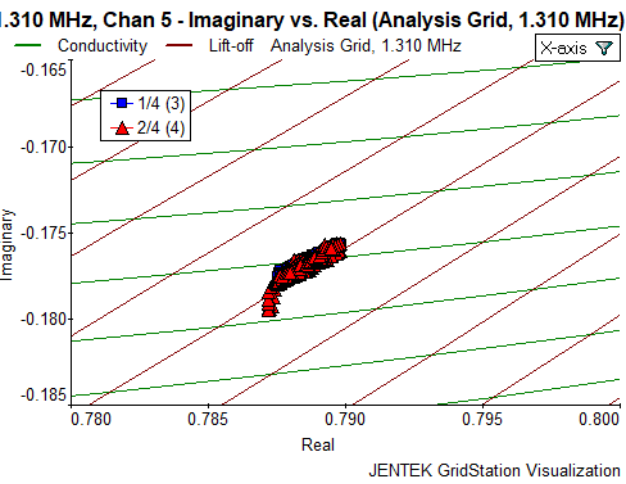
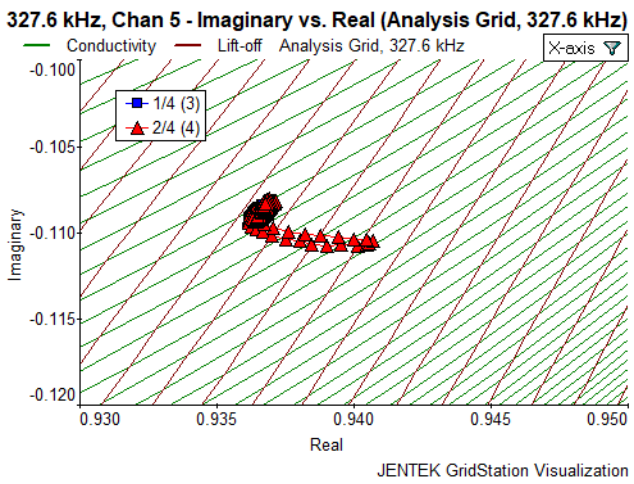
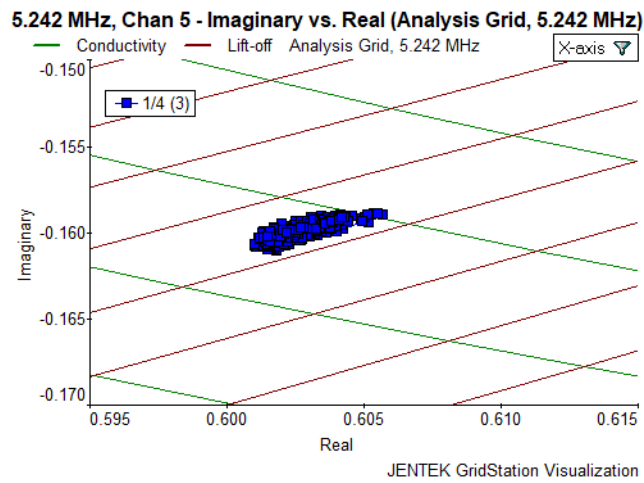
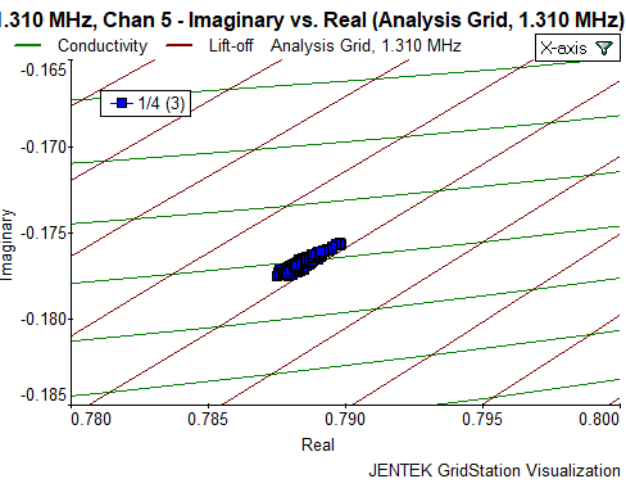
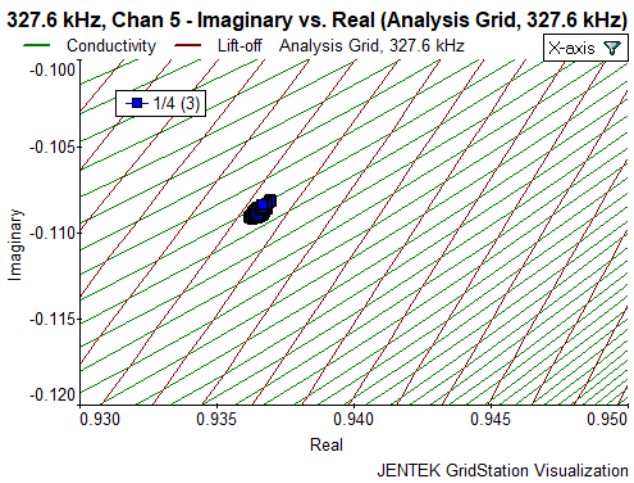


Model-Based visualization

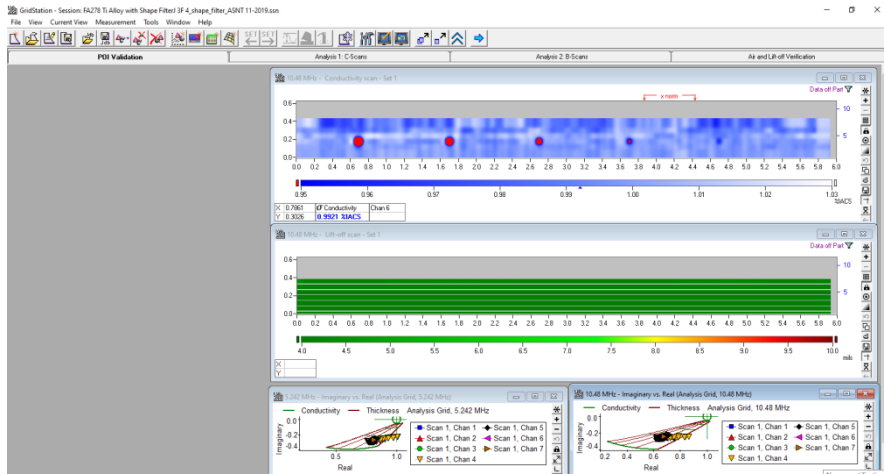
# MIMs– 327 kHz, 1.3 MHz, 5.2 MHz



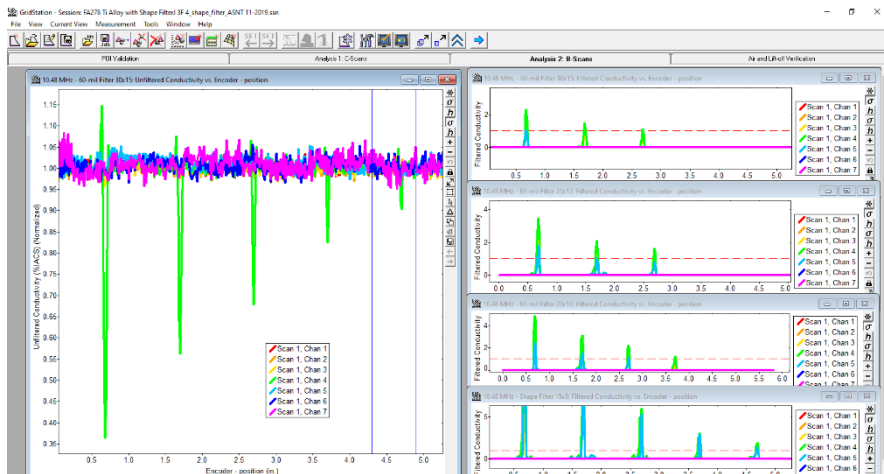
## Model-Based visualization, for Multivariate Inverse Methods (MIM)



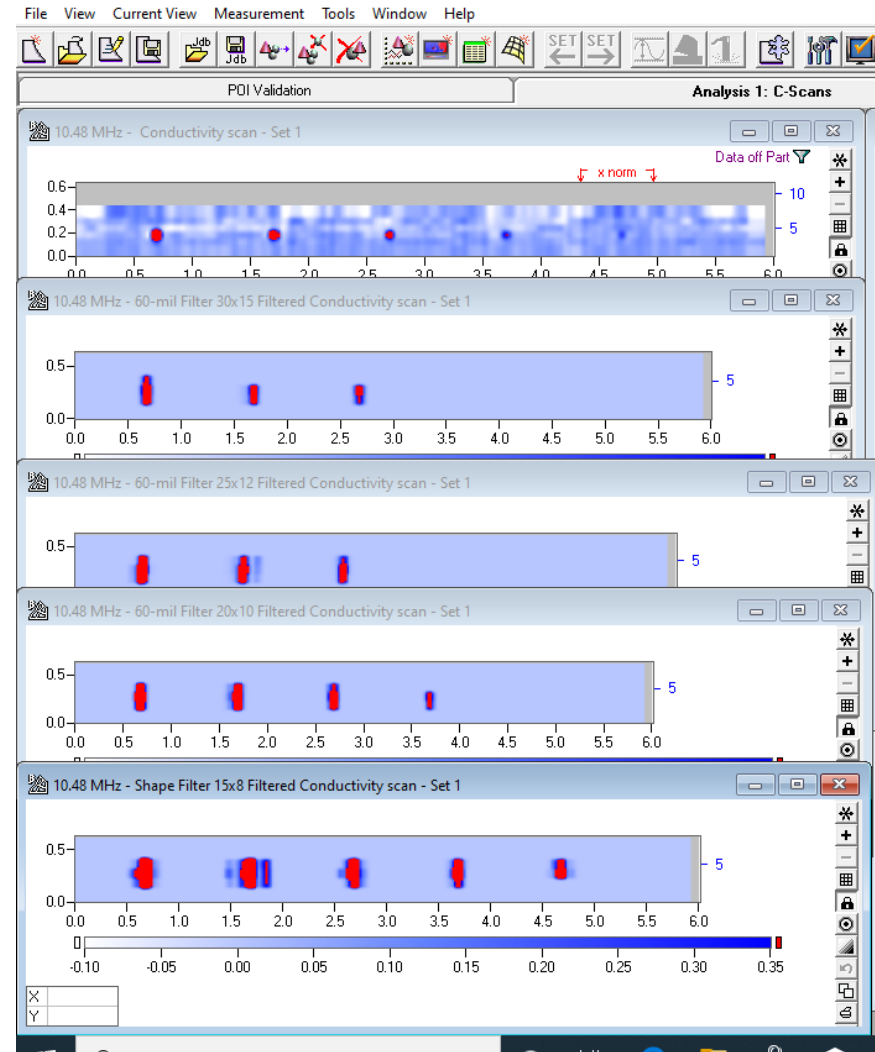
# Surface Crack Detection Interface for POD verification and Inspection



## Liftoff & coverage verification

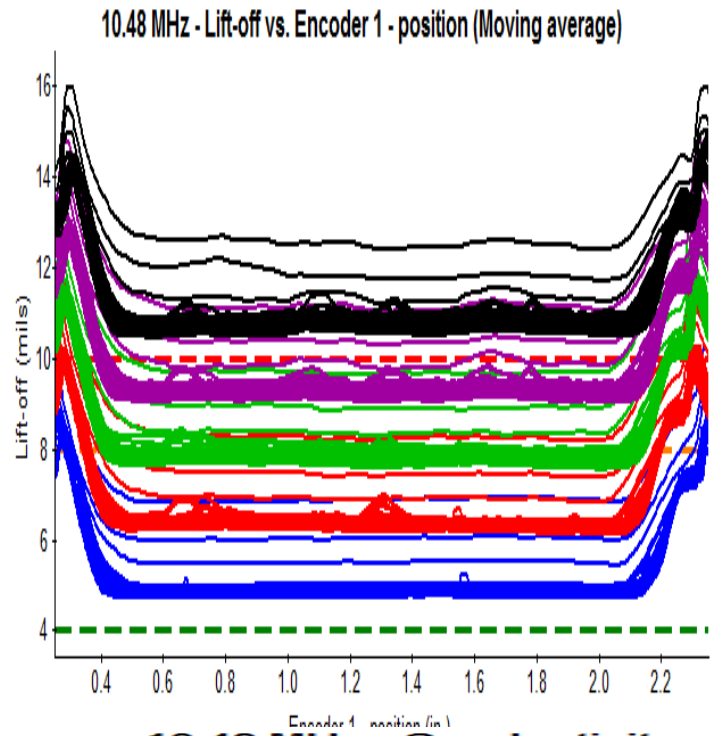


## Unfiltered and Filtered B-Scans

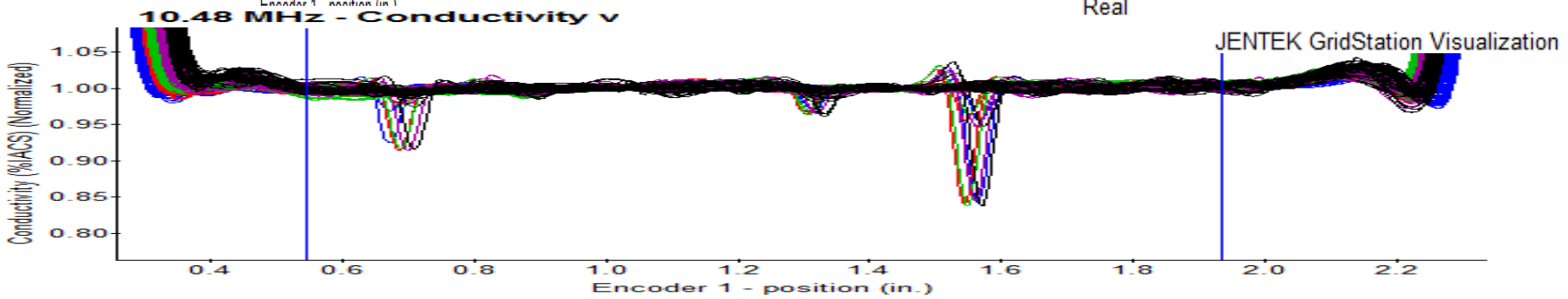
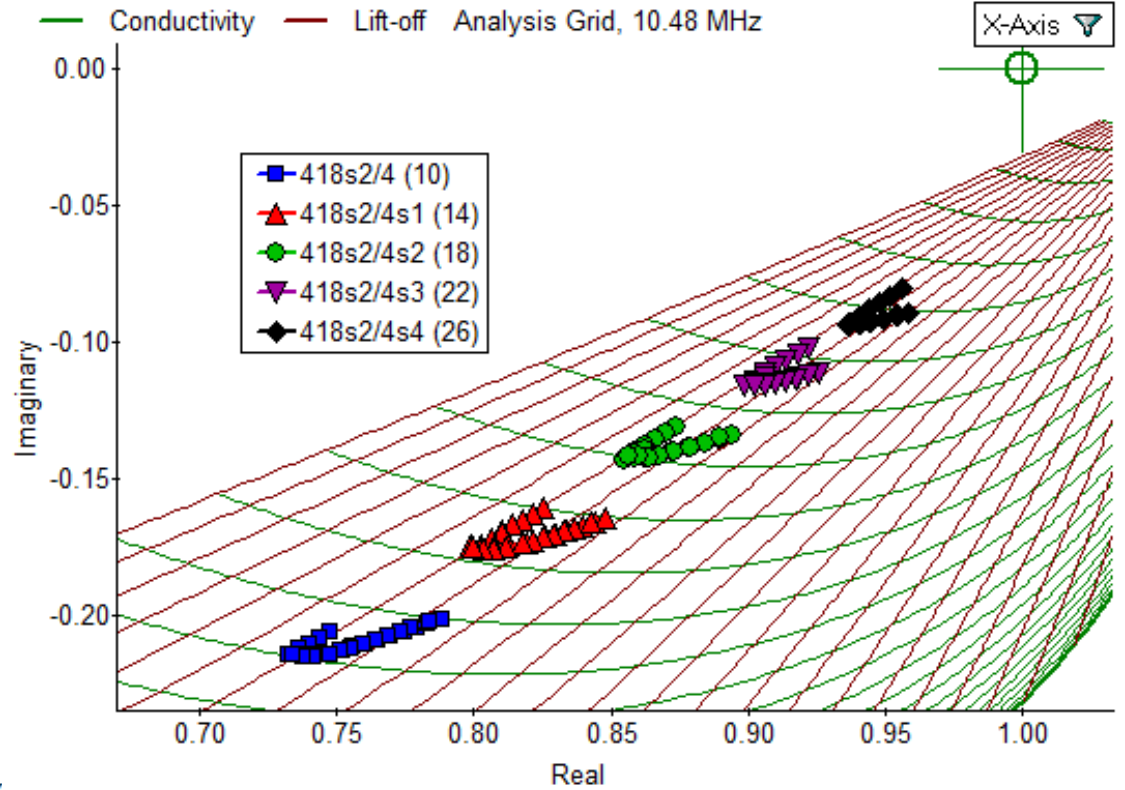


## Unfiltered and Filtered C-Scans

# Surface Cracks: Rescaling of Conductivity Response (evolving jAI)

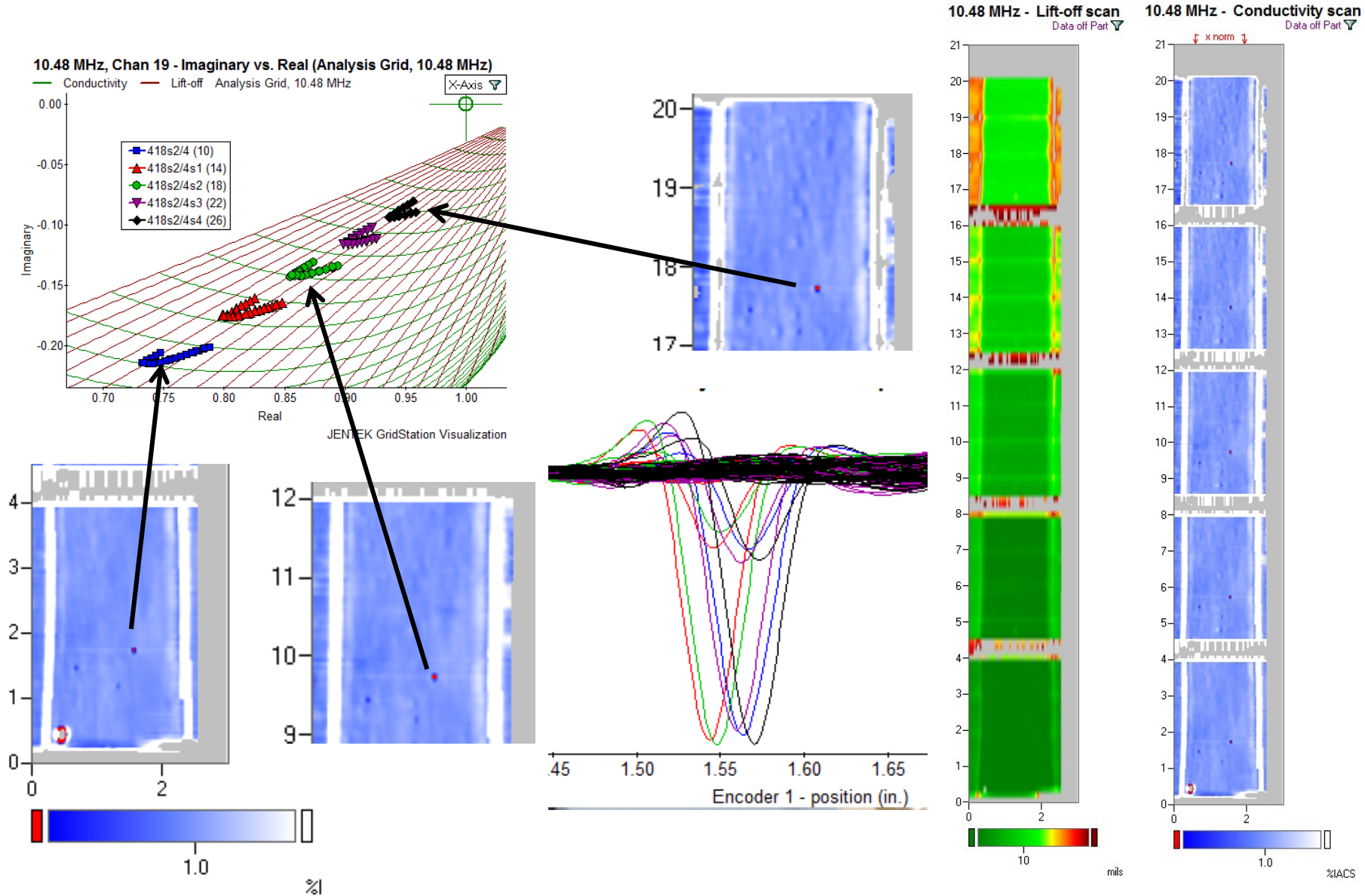


10.48 MHz, Chan 19 - Imaginary vs. Real (Analysis Grid, 10.48 MHz)





# Surface Cracks: Rescaling of Conductivity Response (evolving jAI)

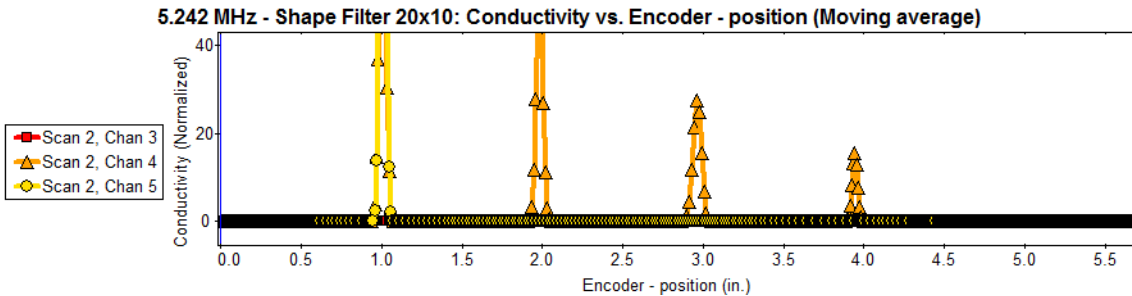
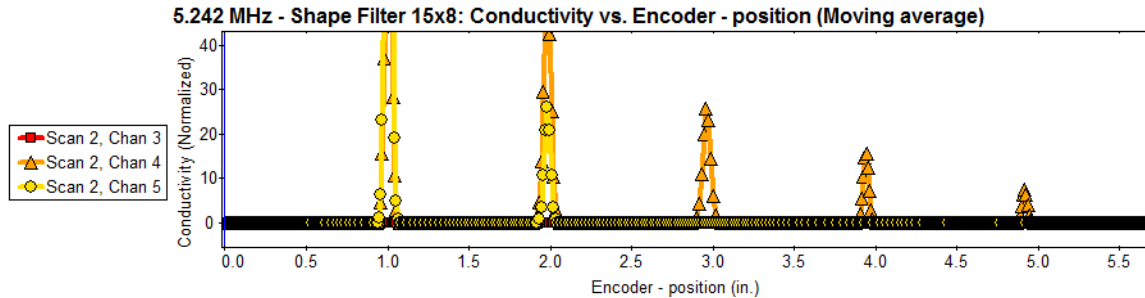
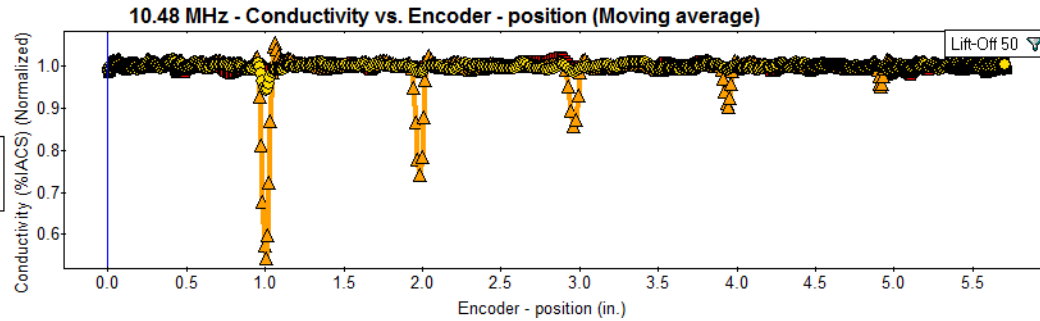


# Titanium Alloy Unfiltered and Shape Filtered Results

EDM Notch Sizes:	length	0.06	0.04	0.03	0.02	0.015
	depth	x0.03	x0.02	x0.015	x0.01	x0.0075



- Scan 2, Chan 3
- ▲ Scan 2, Chan 4
- ◆ Scan 2, Chan 5

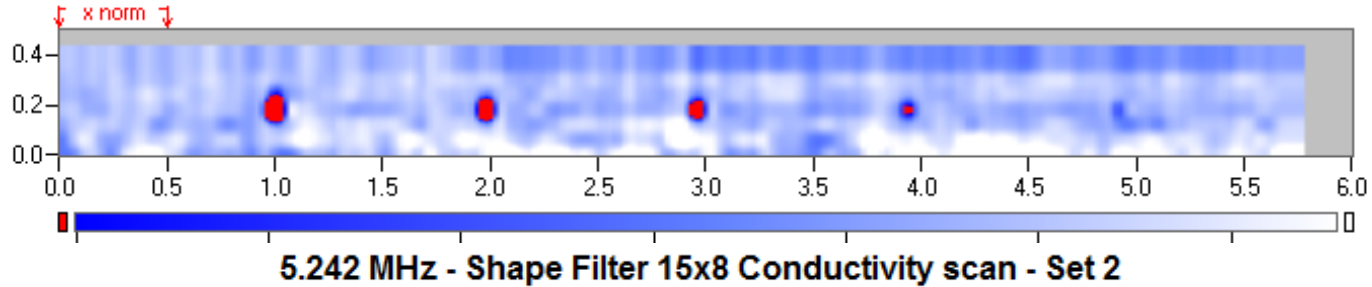


# Titanium Alloy, air calibration, unfiltered and shape filtered results

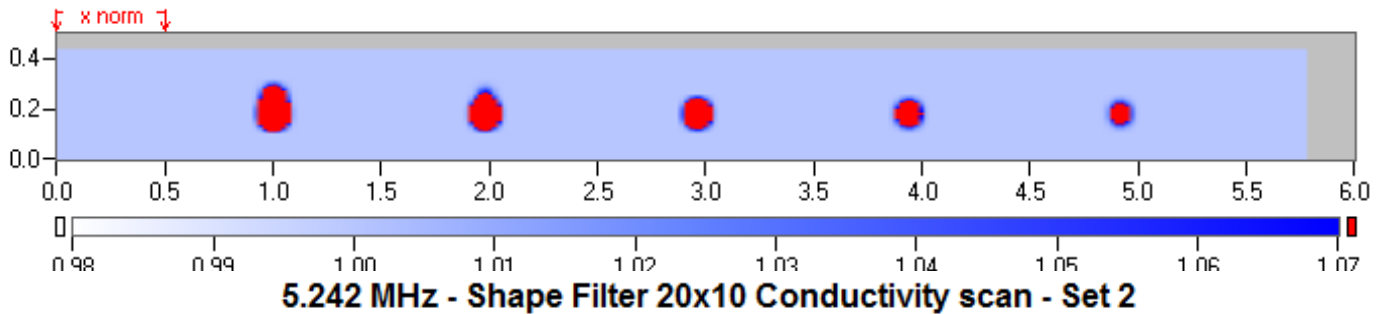
EDM Notch Sizes:	length	0.06	0.04	0.03	0.02	0.015 in.
	depth	x0.03	x0.02	x0.015	x0.01	x0.0075 in.

Lift-Off 50  $\mu$

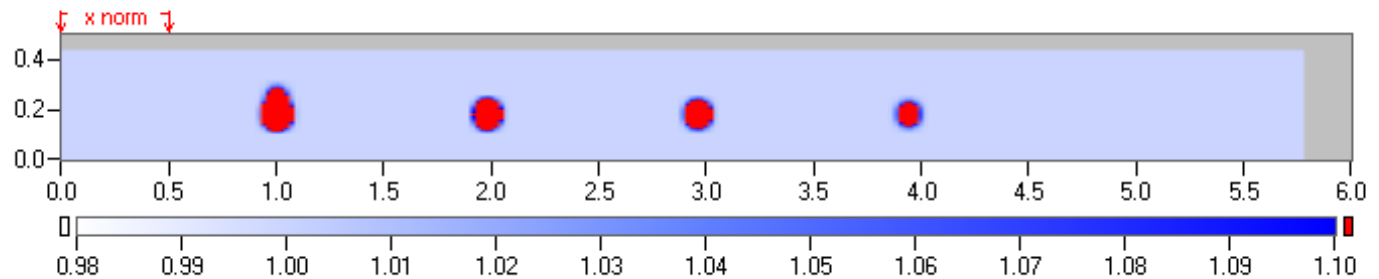
Unfiltered  
5.2MHz  
Conductivity



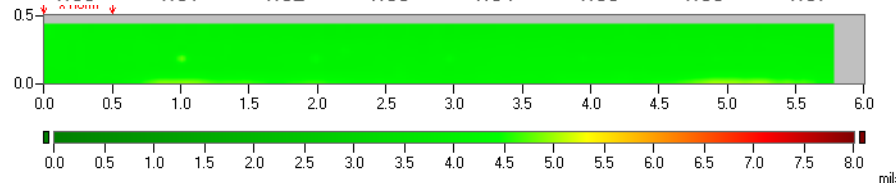
Shape  
Filtered  
0.15 x 0.008



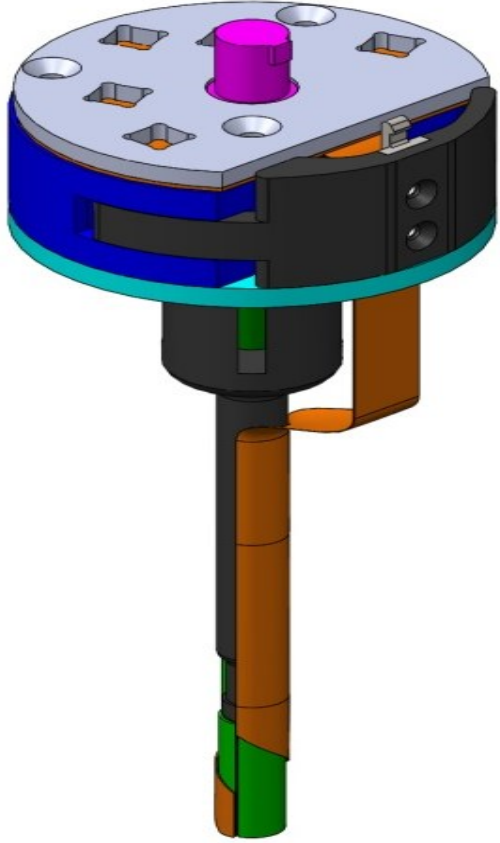
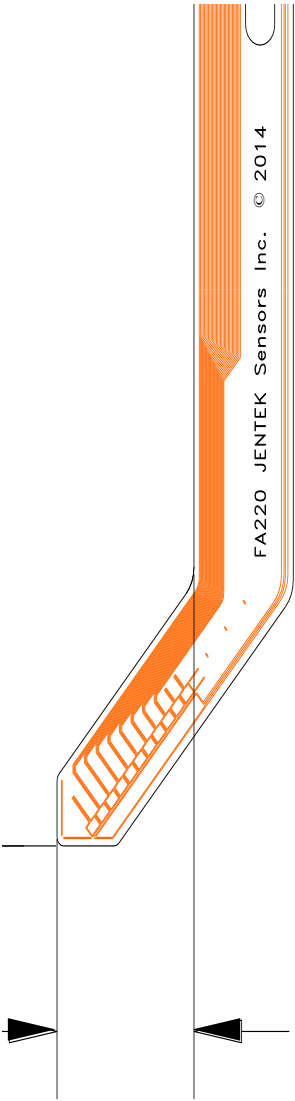
Shape  
Filtered  
0.2 x 0.01



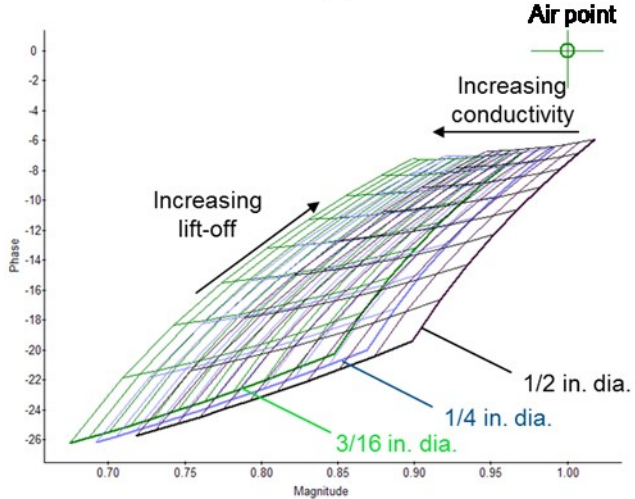
Lift-off  
Verification



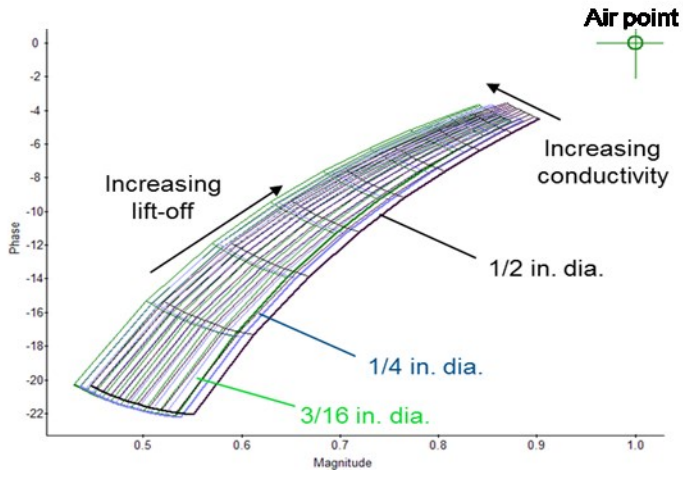
# Bolt Hole Inspection – Hole Diameter Impact



163 kHz



1.31 MHz

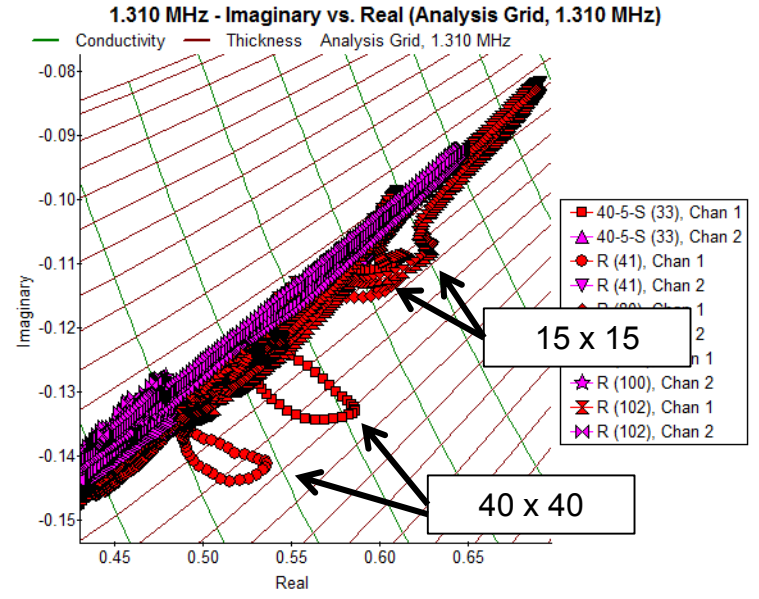
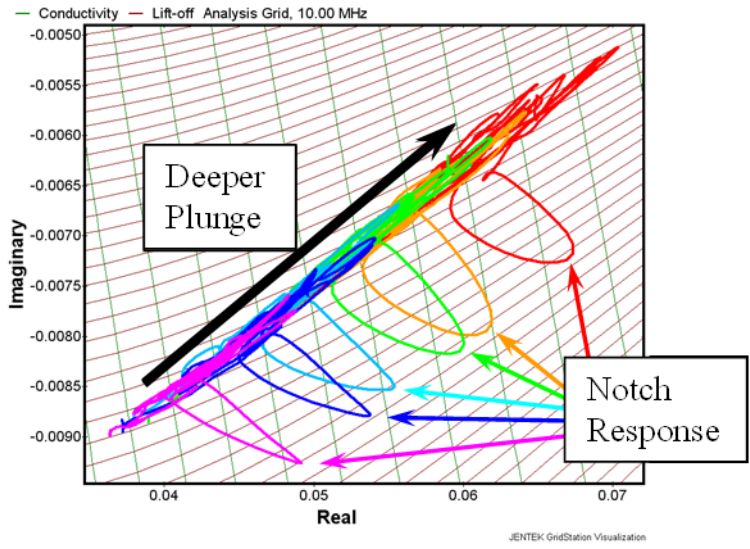
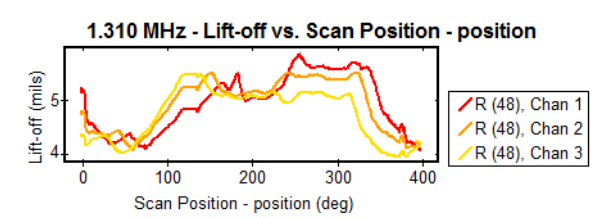
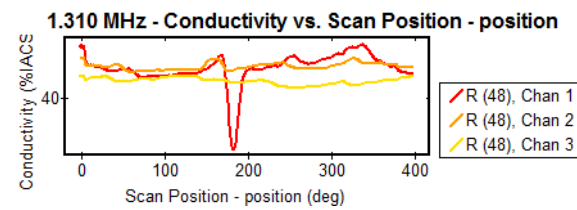
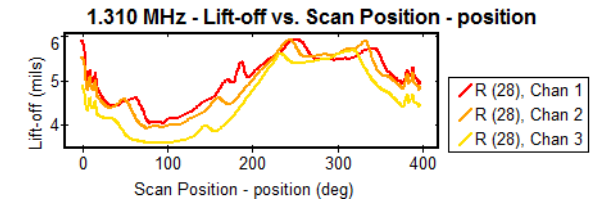
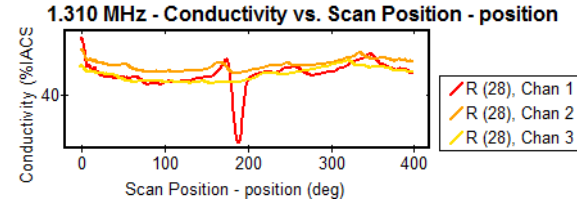


# Bolt Hole Flaw Detection

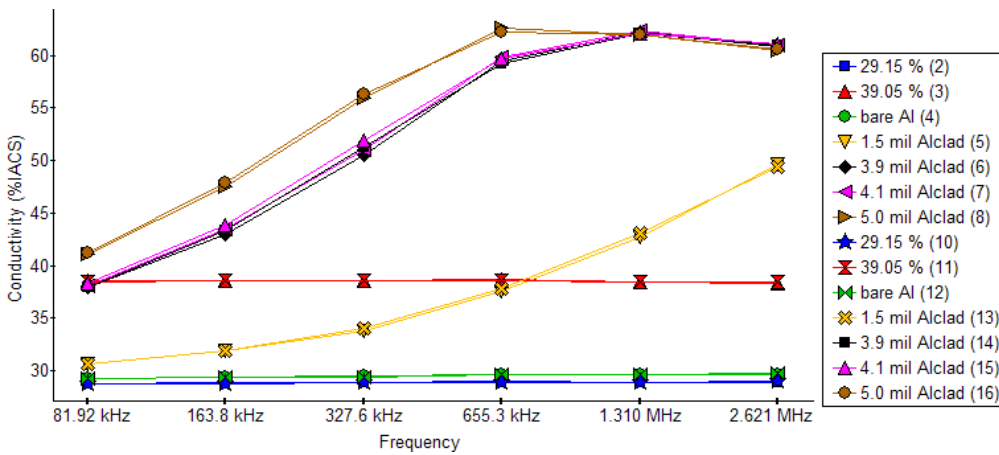
## Automatic rescaling of crack response with varied liftoff

40 x 40 notch (0.001 in.)

30 x 30 notch (0.001 in.)



# Aluminum Cladding Thickness Assessment

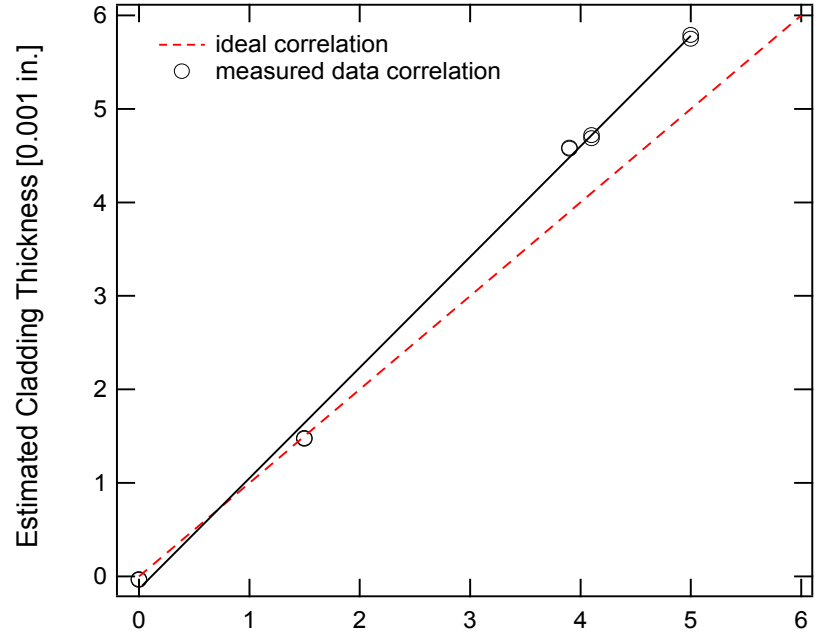


**Needed for accurate corrosion imaging for aircraft structures.**

More than 3 unknowns requires HyperLattice® databases.

- Effective conductivity values for FS42 measurements on clad test coupons and uncoated aluminum alloy samples.

MWM



## Example Ongoing Performance Trials for Aircraft Structures NDT

- Corrosion imaging
- Subsurface crack detection
- Bolt-Hole Inspection

## New Hand-held unit

- More modular and adaptable
- Sensor and accessory kits for easy adaptation

## Tabs for grouping of windows

- Designed for next generation ET Arrays with Model-based methods with digital data archiving
- **POI validation** and operator visualization to aid interpretation

